Strengthening the link between the real and the digital world (/cms/en/about-infineon/company/cypress-acquisition/)
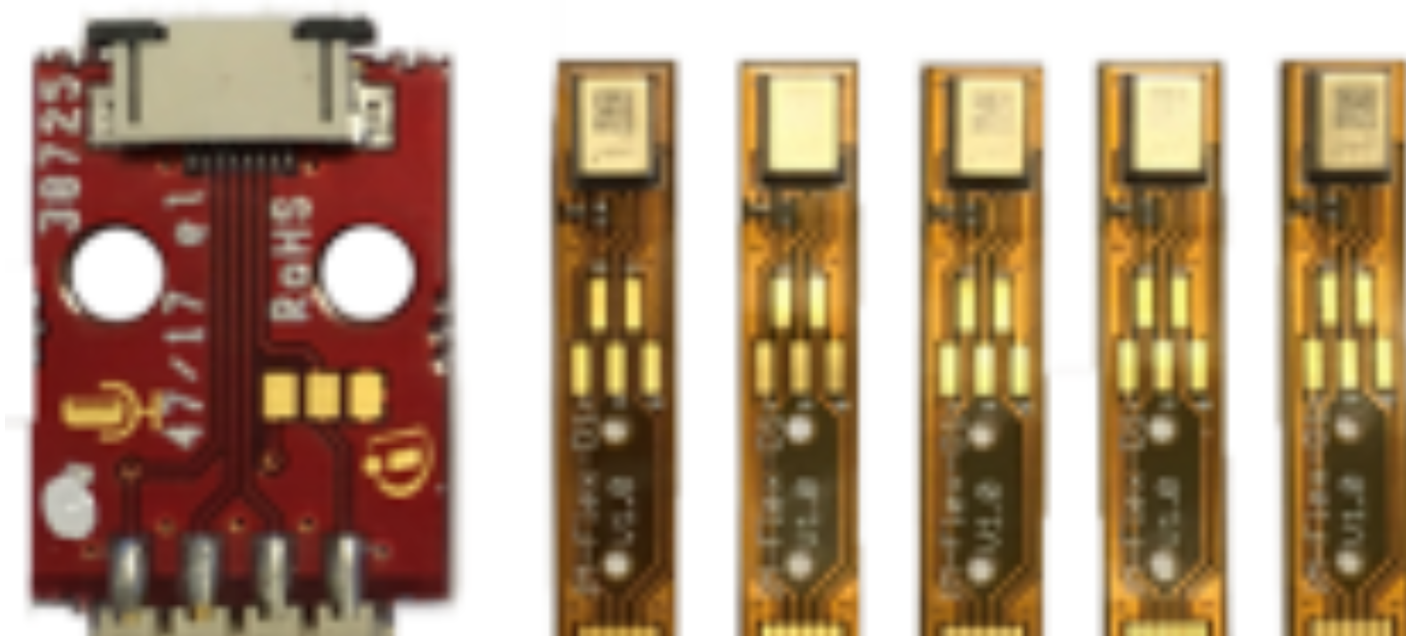
KIT_IM73A135V01_FLEX `NEW`

Overview

Five XENSIV™ MEMS microphones mounted on flex board and one adapter board

The flex evaluation kits allow simple and easy evaluation of XENSIV™ MEMS microphones. One microphone of the respective type is mounted on each flex board. A flex board can be easily connected to an audio testing setup with the included adapter board via a 6-position ZIF connector. Each kit includes five flex boards and one adapter board.

Summary of Features

- Quick and easy connection to evaluation system

- Small size: 25 mm x 4.5 mm

- Pre-soldered MEMS microphone

- Configurable select pin configuration for digital microphones

Parametrics

Parametrics	KIT_IM73A135V01_FLEX
Family	Sensor
Product Description	Flex boards equipped with XENSIV IM73A135V01 MEMS microphone

Order

Sales Product Name	KIT_IM73A135V01_FLEX
OPN ⓘ Info	KITIM73A135V01FLEXTOBO1
Product Status	active
Infineon Package name	--
Standard Package name	
Order online	
Completely lead free	
Halogen free	
RoHS compliant	yes
Packing Size	1
Packing Type	CONTAINER
Moisture Level	
Moisture Packing	NON DRY

Support

Top 6 FAQs. Use the search bar above to show more!

Technical Support

The best way to reach out to our Applications Engineers is through our Developer Community **https://community.infineon.com (https://community.infineon.com)**
Our Applications Engineers moderate the community to ensure all questions are answered quickly and accurately, either by others in the community or by our own engineers.

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Package information

The package information is available on **our homepage (https://www.infineon.com/packages)**. Please note, that they are divided into the subcategories "Leaded and through-hole", "Surface Mounted Devices" and "Special Packages". You will find all relevant package information at the option that applies.

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Notes on processing

Information regarding reflow profile, soldering temperature, soldering profile and further processing notes for most of the discrete products are mentioned in the Application Note.
Please visit **https://www.infineon.com/packages (https://www.infineon.com/packages)** and refer

Please visit **https://www.infineon.com/packages (https://www.infineon.com/packages)** and refer to the document **General Recommendations for Assembly of Infineon Packages (https://www.infineon.com/dgdl/Infineon-…**

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Please select "Simulation Models (SPICE, S-parameters, SABER)"

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